Suss SB8e Substrate Bonder

Manager: Edward Camacho
Backup: Rob Ilic

Safety
- Don't open the chamber manually until the temperature is below 100 C and the gas pressure is above 990 mBar
- No Buddy Restrictions
- Substrates and thermal chuck could be hot after processing

Process Restrictions

Material Restrictions
- Only metals evaporated at the CNF are allowed in the tool.
- Metal and other compression material can only be in the bonding interface
- For running pieces check with tool manager before running the tool.

Parameter Restrictions
- Maximum temperature is 550 C
- Max wafer size is 8 inch (200 mm)
- Max Power Supply 0 to +/- 2000 VDC with maximum current at 15mA
- Max pressure is determined by area, see the chart in the appendix in the back of the manual (p=F/A)

Scheduling / Sign-up Restrictions
- None

Requirements (Do Every Time)
- Remove the 17 Hex #10 crews with the metric Hex drivers
- Edit, check, and load your recipe
- Load your stack
- Run your process

Prohibitions (Never Do)
- DO NOT use Wet Chemistry on the tool.
- DO NOT exceed tool's process parameters.

Common Problems

<table>
<thead>
<tr>
<th>Problem:</th>
<th>Root Cause:</th>
<th>Solution:</th>
</tr>
</thead>
<tbody>
<tr>
<td>Top Tool Error</td>
<td>Top tool could not be moved up</td>
<td>Push the Retry button. This resends the signal to bring the pressure tool up.</td>
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</tbody>
</table>

Other Comments or Cautions
- Make sure to clean substrate before bonding
- Talk to the tool manager before processing pieces
- See pages 5-24 and up for error descriptions and required actions.

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